



# LGA/BGA SOCKET FOR HIGH PERFORMANCE ASICS

## Features:

- Top & bottom pressure mount contacts with over stress prevention.
- Built in plastic device bias springs (when supplied) provide accurate device registration.
- Offset radial contact with BGA device solderballs does not alter solderball bottom surface.
- Small to high I/O applications can be quoted.

## Specifications

- Beryllium Copper Alloy with 30µ" gold per MIL-G45204 over 50µ" nickel per QQ-N-290.

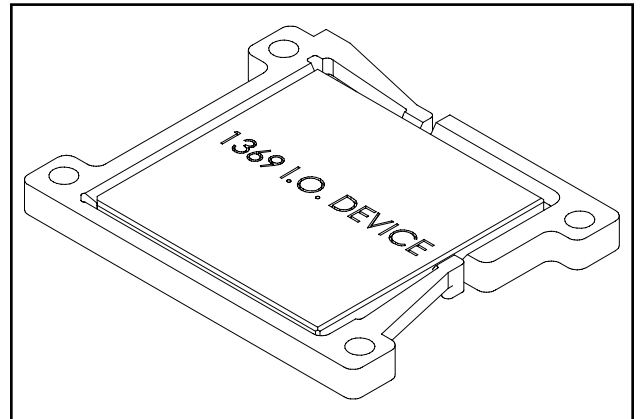
## Hi-temperature LCP.

## Mounting Considerations

- .020"/.025" dia. contact pad w/30µ" gold plating per MIL-G-452-4 on 1.00mm±.05mm pitch in x & y directions in array required.

ALL DIMENSIONS: INCHES [MILLIMETERS]

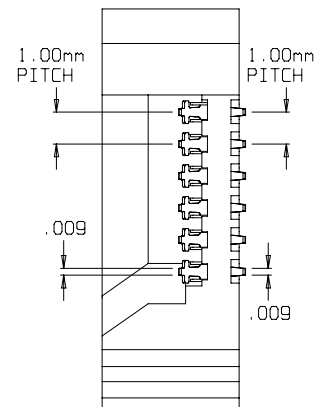
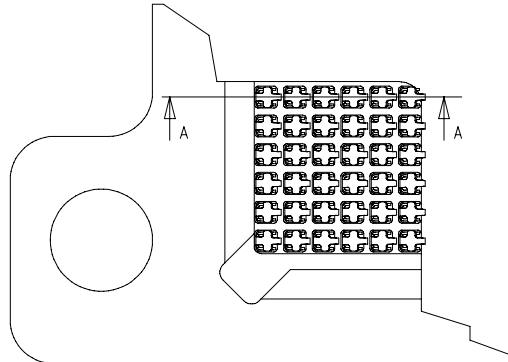
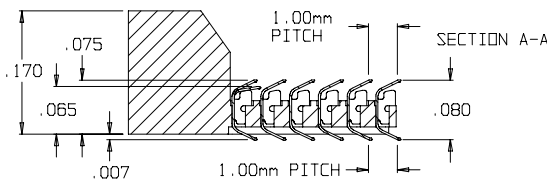
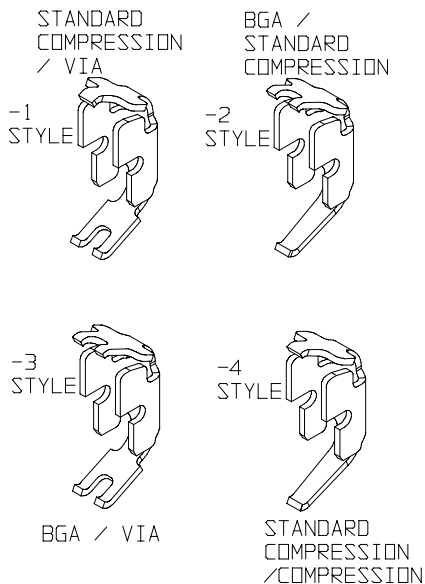
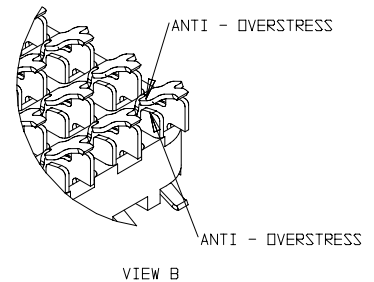
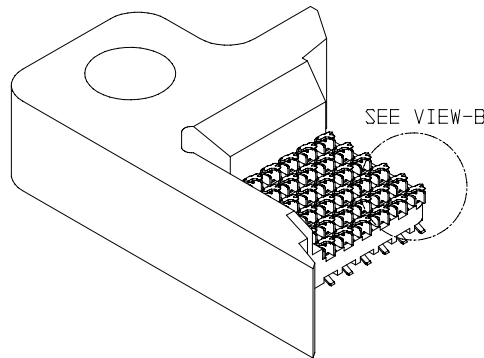
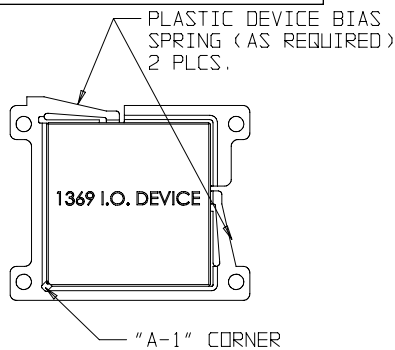
All tolerances ± .005 [.13] unless otherwise specified



*Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.*

## ORDERING INFORMATION

Consult Factory for Part Numbers and Quotes



<http://www.arieselec.com> • [info@arieselec.com](mailto:info@arieselec.com)

**NORTH AMERICA**  
 Frenchtown, NJ USA  
 TEL: (908) 996-6841  
 FAX: (908) 996-3891



**UK/IRELAND/GB**  
 TEL: +44 870 240 0249  
 FAX: +44 1653 600493  
[uking@arieselec.com](mailto:uking@arieselec.com)

**EUROPE/MAINLAND/HOL**  
 TEL: +31 78 615 94 65  
 FAX: +31 78 615 43 11  
[europe@arieselec.com](mailto:europe@arieselec.com)

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 REV.A